

NO-CLEAN DESOLDERING WICK

Static-free desoldering and repair of PC boards

DESCRIPTION

The Stannol No-Clean Desoldering Wick was designed for static-free desoldering and repair of PC boards without the need for subsequent cleaning. It uses a special halide-free vacuumised No-Clean, flux-coated copper braid designed to improve wicking. It will not lose its efficiency even after prolonged storage in humid conditions. The wick remains flexible and will not flake. Stannol No-Clean wick is available in 4 sizes. Each size has colour coded packaging for easy identification:

SIZE REFERENCE	WIDTH*	COLOUR CODE
NC-00:	0.8 mm	white
NC-AA:	1.5 mm	orange
NC-AB:	2.2 mm	green
NC-BB:	2.7 mm	blue

* The values given in the data sheet are nominal values. The width may change slightly during the manufacturing process.

CHARACTERISTICS

This products offers the following advantages:

- **Faster and increased solder absorption**
- **Wound on static dissipative spools (only 1.5 m spools)**
- **PCBs will meet MIL-P-28809A Cleanliness Test without cleaning**
- **Negligible residues which are non-corrosive, clear and non-hygroscopic**
- **Heat stable coating**
- **Vacuum packed**
- **Excellent shelf life**

APPLICATION

Lay Stannol No-Clean Wick over the solder requiring removal and place the soldering iron tip on top of the copper braid. The braid and solder beneath will gradually heat until the solder melts and is absorbed into the braid by capillary action. Remove the braid, cut off the solder-filled length. Sudden heat shock, which may be produced when using a preheated vacuum desoldering tool, is prevented since the braid is cold when it first comes into contact with the joint to be desoldered.

SPECIAL PROPERTIES

Stannol No-Clean Wick is supplied on static dissipative spools conforming to both (DOD) Standard 1686 and DOD Handbook 263 for static discharge protection and meets the decay rate provision of MIL-B-81705B.

Specially processed copper braid is coated with a reduced volume of a special halide free synthetic resin, so that the quantity of residue after use is significantly less than with conventional desoldering wick. PCBs will pass the MIL-P-28809A Cleanliness Test without cleaning, provided a No-Clean flux and a clean system and components are used. PCBs will also pass this test if they have been cleaned after the soldering operation, provided they have been reworked using a No-Clean flux in a clean environment. No-clean flux classified as type RELO according to J-STD-004.

PACKAGING

Stannol No-Clean Wick is supplied in static dissipative plastic spools of 1.5m each. This provides convenient application and protects the user from heat. The static dissipative spools per vacuum packed sleeve. Also available in 30.48 m spools (not static dissipative).

SHELF-LIFE

Due to the special coating, Stannol No-Clean Wick does not lose its efficiency even after prolonged storage in humid conditions, whereas conventional rosin coated wicks may lose their efficiency under such conditions. The shelf life is minimum 2 years (provided proper storage and originally sealed package).

DISPOSAL

Do not dispose of in the domestic waste, but give to recycling with metalliferous waste.

Attention: Dispose of lead contaminated wicks properly!

HEALTH AND SAFETY

Before using please read the material safety data sheet carefully and observe the safety precautions described.

NOTE

The above values are typical and represent no form of specification. The Data Sheet serves for information purposes. Any verbal or written advise is not binding for the company, whether such information originates from the company offices or from a sales representative. This is also in respect of any protection rights of third parties, and does not release the customer from the responsibility of verifying the products of the company for suitability of use for the intended process or purpose. Should any liability on the part of the company arise, the company will only indemnify for loss or damage to the same extent as for defects in quality.